

HD74HCT564, HD74HCT574

Octal D-type Flip-Flops (with 3-state outputs)

REJ03D0670-0200 (Previous ADE-205-560) Rev.2.00 Mar 30, 2006

Description

These devices are positive edge triggered flip-flops. The difference between HD74HCT564 and HD74HCT574 is only that the former has inverting outputs and the latter has noninvertering outputs.

Data at the D inputs, meeting the set-up and hold time requirements, are transferred to the Q or \overline{Q} outputs on positive going transitions of the clock (CK) input. when a high logic level is applied to the output control (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

Features

• LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility

• High Speed Operation: t_{pd} (D to Q, \overline{Q}) = 15 ns typ ($C_L = 50 \text{ pF}$)

High Output Current: Fanout of 15 LSTTL Loads
 Wide Operating Voltage: V_{CC} = 4.5 to 5.5 V

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)	
HD74HCT564P	DILP-20 pin	PRDP0020AC-B	P		
HD74HCT574P	DILP-20 PIII	(DP-20NEV)		_	
HD74HCT564FPEL	COD 20 pin / IFITA)	PRSP0020DD-B	FP	FL (2.000 = cc/rccl)	
HD74HCT574FPEL	SOP-20 pin (JEITA)	(FP-20DAV)		EL (2,000 pcs/reel)	
HD74HCT564RPEL	COD 20 pin (JEDEC)	PRSP0020DC-A	RP	FL (4.000 pag/ragl)	
HD74HCT574RPEL	SOP-20 pin (JEDEC)	(FP-20DBV)	KP	EL (1,000 pcs/reel)	

Note: Please consult the sales office for the above package availability.

Function Table

	Inputs	Outputs		
Output Control	Clock	Data	HD74HCT564	HD74HCT574
L		Н	L	Н
L		L	Н	L
L	L	X	Q_0	Q_0
Н	X	X	Z	Z

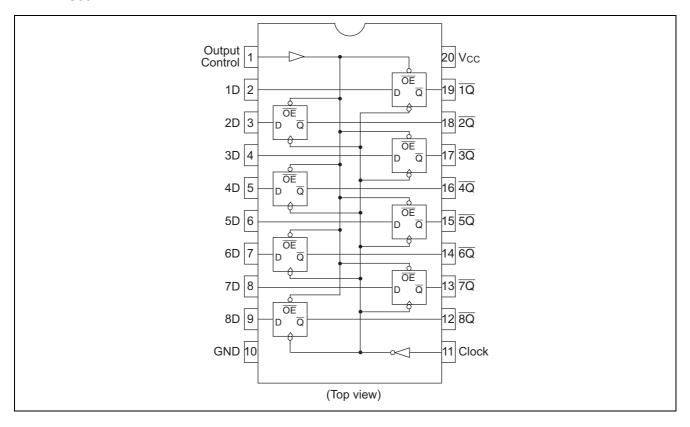
Q₀: level of Q before the indicated Steady-sate input conditions were established.

 \overline{Q}_0 : complement of Q_0 or level of \overline{Q} before the indicated Steady-state input Conditions were established.

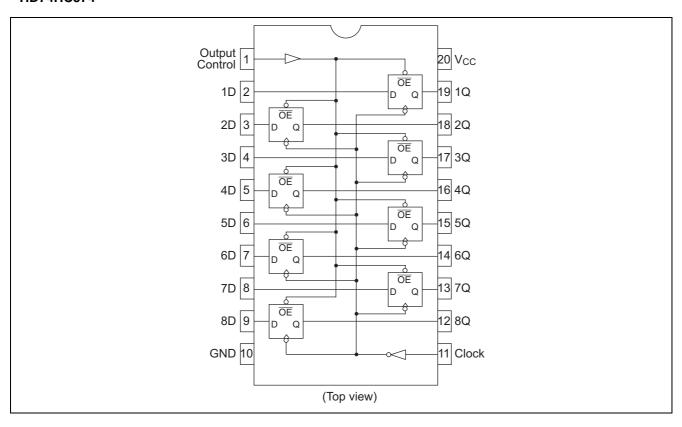


Pin Arrangement

HD74HC564

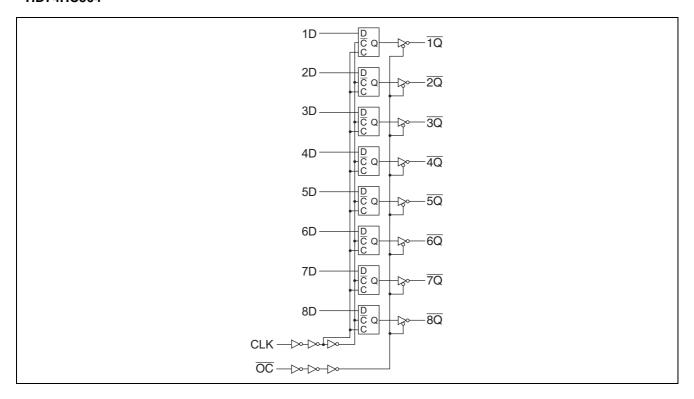


HD74HC574

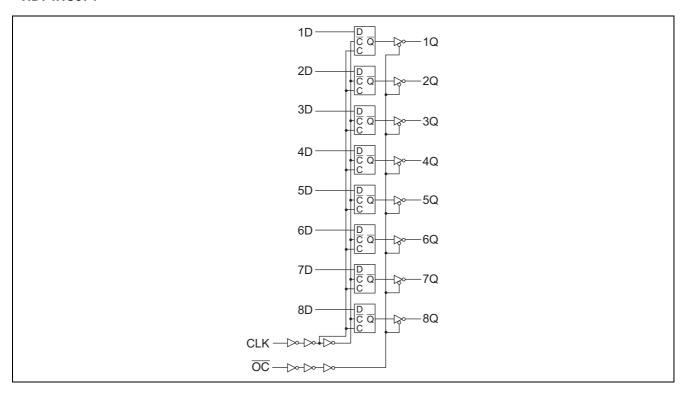


Logic Diagram

HD74HC564



HD74HC574



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V _{CC}	-0.5 to 7.0	V
Input / Output voltage	V _{IN} , V _{OUT}	-0.5 to V_{CC} +0.5	V
Input / Output diode current	I _{IK} , I _{OK}	±20	mA
Output current	Io	±35	mA
V _{CC} , GND current	I _{CC} or I _{GND}	±75	mA
Power dissipation	P _T	500	mW
Storage temperature	Tstg	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	4.5 to 5.5	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V _{CC}	V	
Operating temperature	Та	-40 to 85	°C	
Input rise / fall time*1	t _r , t _f	0 to 500	ns	V _{CC} = 4.5 V

Notes: 1. This item guarantees maximum limit when one input switches. Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

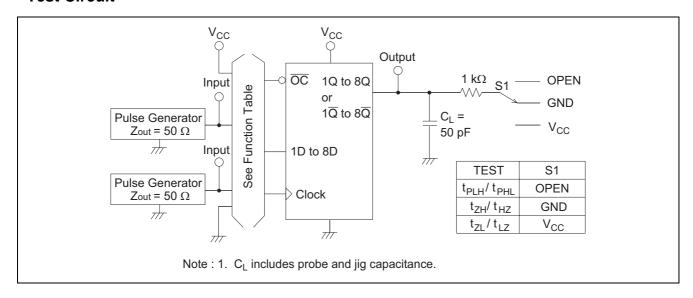
Item	Symbol	V _{cc} (V)	Т	Ta = 25°C Ta = -40 to+85°			to+85°C	Unit	Test Conditions	
item	Symbol	VCC (V)	Min	Тур	Max	Min	Max	Oilit	rest Conditions	
Input voltage	V _{IH}	4.5 to 5.5	2.0	_	_	2.0	_	V		
	V _{IL}	4.5 to 5.5	_	_	8.0	_	0.8	V		
Output voltage	V _{OH}	4.5	4.4	_	_	4.4	_	V	Vin = V_{IH} or V_{IL} $I_{OH} = -20 \mu A$	
		4.5	4.18	_	_	4.13	_		$I_{OH} = -6 \text{ mA}$	
	V _{OL}	4.5	_	_	0.1	_	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 μ A	
		4.5	_	_	0.26	_	0.33		$I_{OL} = 6 \text{ mA}$	
Off-state output	loz	5.5	_	_	±0.5	_	±5.0	μΑ	$Vin = V_{IH} \text{ or } V_{IL},$	
current									Vout = V_{CC} or GND	
Input current	lin	5.5	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND	
Quiescent current	Icc	5.5	_	_	4.0	_	40	μΑ	Vin = V_{CC} or GND, lout = 0μ	

Switching Characteristics

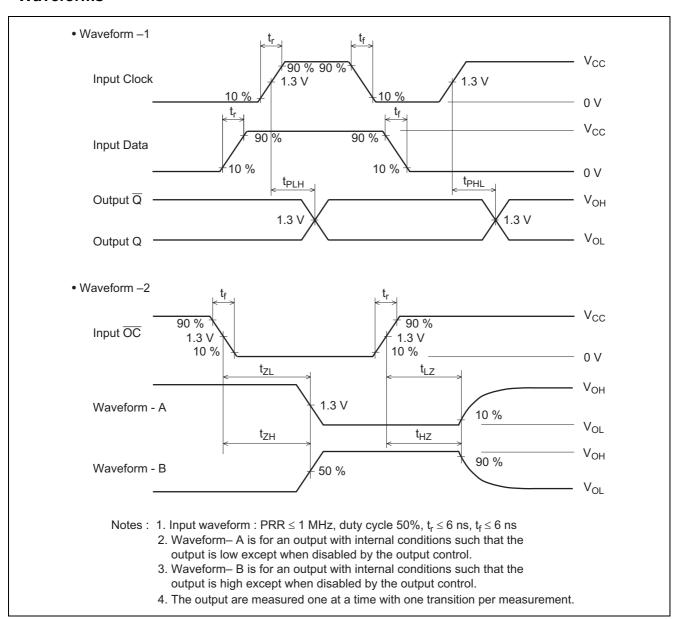
 $(C_L = 50 \text{ pF, Input } t_r = t_f = 6 \text{ ns})$

Itam	Cymhal	V 00	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions	
Item	Symbol	V _{CC} (V)	Min	Тур	Max	Min	Max	Onit	rest Conditions
Maximum clock frequency	f _{max}	4.5			30	_	24	ns	
Propagation delay time	t _{PLH}	4.5		14	31	_	39	ns	
	t _{PHL}	4.5	_	15	31	_	39		
Output enable time	t _{ZL}	4.5	_	16	30	_	38	ns	
	t _{zH}	4.5	_	16	30	_	38		
Output disable time	t _{LZ}	4.5	_	15	30	_	38	ns	
	t _{HZ}	4.5	_	18	30	_	38		
Setup time	t _{su}	4.5	20	3	_	25	_	ns	
Hold time	t _h	4.5	5	-2	_	5	_	ns	
Pulse width	t _w	4.5	16	7	_	20	_	ns	
Output rise/fall time	t _{TLH}	4.5		4	12	_	15	ns	
	t _{THL}	4.5		4	12	_	15		
Input capacitance	Cin	_		5	10	_	10	pF	

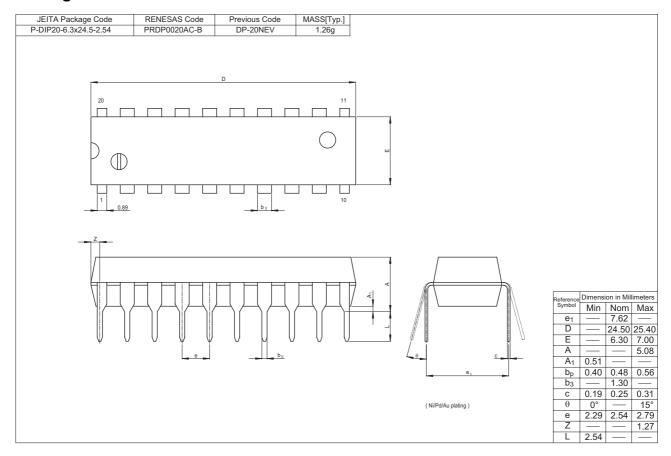
Test Circuit

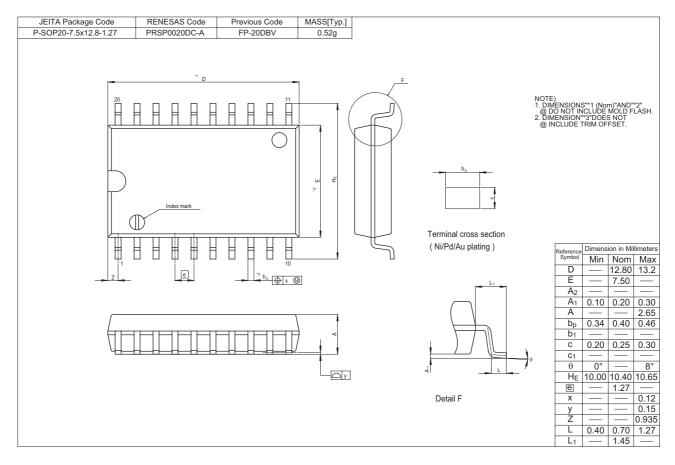


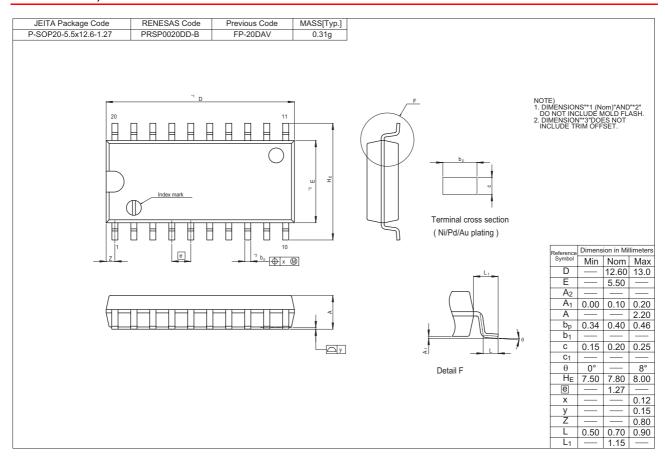
Waveforms



Package Dimensions







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